



ALLIANCE MEMORY MDS REPORT

Part Number:		AS4C256M8D3LB-12BCN/AS4C256M8D3LB-12BIN/AS4C256M8D3LB-12BAN							
Part Weight:		206.49133mg							
No.	Part Name	Material Name	Component wt (mg)	Material Content (Element)	CAS Number	Element wt (%)	Element wt (mg)	wt % of Total unit wt	PPM
1	Substrate	HL-832NXA / AUS 308	68.2	Bismaleimide Triazine resin, Epoxy resin, other resin	Not applicable	14.75%	10.05634	4.87%	147453
				Inorganic Filler	Not applicable	12.48%	8.50921	4.12%	124768
				Continuous Filament Fiber Glass	65997-17-3	18.15%	12.37703	5.99%	181481
				Talc containing no asbestiform fibers	14807-96-6	0.54%	0.37067	0.18%	5435
				Morpholine derivative	Trade secret	0.54%	0.37067	0.18%	5435
				Barium sulfate	7727-43-7	3.26%	2.22400	1.08%	32610
				Silica, amorphous	7631-86-9	0.14%	0.09267	0.04%	1359
				Dipropylene glycol monomethyl ether	34590-94-8	1.09%	0.74133	0.36%	10870
				Naphthalene	91-20-3	0.14%	0.09267	0.04%	1359
				Epoxy resin A	Trade secret	1.77%	1.20467	0.58%	17664
				Epoxy resin B	85954-11-6	1.22%	0.83400	0.40%	12229
				Barium sulfate	7727-43-7	2.72%	1.85333	0.90%	27175
				Dipropylene glycol monomethyl ether	34590-94-8	2.17%	1.48267	0.72%	21740
				Copper	7440-50-8	38.94%	26.55911	12.86%	389430
				Nickel	7440-02-0	1.86%	1.26778	0.61%	18589
God	7440-57-5	0.24%	0.16387	0.08%	2403				
2	Die Adhesive	6202C	0.28446	Butadiene, acrylonitrile polymer, carboxy-terminated, polymer with bisphenol A and epichlorohydrin	68610-41-3	27.00%	0.07680	0.04%	270000
				2-(2-Ethoxyethoxy)ethyl acetate	112-15-2	38.00%	0.10809	0.05%	380000
				Silica Filler	112926-00-8	27.00%	0.07680	0.04%	270000
				Isodecyl alcohol, ethoxylated	61827-42-7	7.30%	0.02077	0.01%	73000
				tert-butyl peroxyneodecanoate	26748-41-4	0.70%	0.00199	0.00%	7000
3	Gold Wire	Au	0.5582	Gold	7440-57-5	100.00%	0.55820	0.27%	1000000
4	Compound	CEL-9120HF	109.91095	epoxy resin1	Trade secret	3.50%	3.84688	1.86%	35000
				epoxy resin1	Trade secret	2.00%	2.19822	1.06%	20000
				Phenol Rsin	Trade secret	4.00%	4.39644	2.13%	40000
				Carbon black	1333-84-6	0.20%	0.21982	0.11%	2000
				Metal hydroxide	Trade secret	10.00%	10.99110	5.32%	100000
				Amorphous silica	60676-86-0	80.00%	87.92876	42.58%	800000
				Crystal	14808-60-7	0.30%	0.32973	0.16%	3000
5	Solder Ball	Sn/Ag/Cu	27.5184	Tin	7440-31-5	96.80%	26.63781	12.90%	968000
				Silver	7440-22-4	3.00%	0.82555	0.40%	30000
				Copper	7440-50-8	0.20%	0.05504	0.03%	2000
6	Chip	Chip	0.01932	Silicon	7440-21-3	100.00%	0.01932	0.01%	1000000
						600.00%	206.49133	100.00%	6000000